



PROTEUS HIGH THROUGHPUT MODE

VERSION 1.5

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Revision history

Manual version	Notes	Date
1.0	 Initial version 	November 2018
1.1	 Updated file name to new AppNote name structure. Updated important notes, legal notice & license terms chapters. 	June 2019
1.2	 Updated address of Division Wireless Connectivity & Sensors location 	October 2019
1.3	 Added new test results of Proteus-II and Proteus-III 	February 2020
1.4	 Added new test results of the Proteus-III-SPI 	February 2021
1.5	• Updated Important notes, meta data and document style	July 2023



Abbreviations

Abbreviation	Name	Description
Payload		The intended message in a frame / package.
RF	Radio frequency	Describes wireless transmission.
UART	Universal Asynchronous Receiver Transmitter	Allows the serial communication with the module.
[HEX] 0xhh	Hexadecimal	All numbers beginning with 0x are hexadecimal numbers. All other numbers are decimal, unless stated otherwise.

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1 Introduction

The Proteus series is a product series of Bluetooth[®] modules based on the nRF52 Nordic Semiconductors SoC which presents various Bluetooth[®] LE and low power features.

Bluetooth[®] LE enabled devices allow to transmit/receive data in a short interval after the connection event. During this period, by default one data packet of up to 251 Bytes is transmitted from master to slave and one data packet from slave to master. After the transmission, the device goes to sleep until the next connection event occurs (see figure 1).





Due to this procedure, the device is suited for low power applications, but it's default radio throughput is limited¹ to:

$$\frac{\text{Data per packet}}{\text{Connection interval}} [Byte/s] \tag{1}$$

To overcome this limitation, for Proteus-II and Proteus-III a new mode has been introduced. This so called "high throughput mode" enables to transmit/receive up to 4 Bluetooth[®] LE packets per connection interval (see figure 2). With this the throughput of a Bluetooth[®] LE connection can be increased, at the expense of a higher energy consumption.

¹Please note that there are further conditions that slow down the throughput, like the UART speed and the μ C processor speed.





Figure 2: Improved data transmission with up to 4 packets per connection interval

1.1 Compatibility and risks

By default Bluetooth[®] LE enabled devices support the transmission of one data packet in a short period after the connection event. With upcoming new Bluetooth[®] LE devices an increasing number of data packets per connection interval is supported. Modern iOS devices support up to 4 packets, Android devices support up to 6 packets per connection interval:

Device	Number of packets per connection interval		
Samsung Galaxy S8	4		
Nexus 4, Nexus 6P	6		
OnePlus 5	6		
iPhone 6, 7, Xs	4		

Table 1: Examples of Bluetooth® LE enabled devices supporting this feature

As only one packet per connection interval must be supported by a Bluetooth[®] LE connection, there is always a risk that the connection partner does not support this feature.



2 Usage

To enable the high throughput mode the corresponding bit in the CFG_Flags has to be set by using the CMD_SET_REQ command.

2.1 Maximum packet size

During the connection setup the module outputs a CMD_CHANNELOPEN_RSP message on the UART. This message contains the maximum payload of a standard packet (Φ_{ST}). Keeping this value in mind, the maximum packet to be transmitted via the CMD_DATA_REQ in high throughput mode is calculated as:

$$\Phi_{HTM} = (\Phi_{ST} - 2) \times 4[Bytes] \tag{2}$$

In case of the largest maximum transmission unit (MTU), that is supported by the Proteus modules, the size of the standard packet Φ_{ST} is 243 (0xF3) Bytes. Therefore, the largest packet size Φ_{HTM} in high throughput mode calculates as 964 Bytes.

2.2 Bluetooth LE packet format

The standard Bluetooth[®] LE packet of a Proteus module has the following format:

Bluetooth [®] LE Payload			
Header Payload data			
0x01	Φ_{ST} Bytes		

Table 2: RF-packet for	ormat to transmit data
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Using that frame format one packet is sent per connection interval. To increase throughput, the new frame format

Bluetooth [®] LE Payload					
Header Sequence number Fragment ID Payload data					
0x04	1 Byte	1 Byte	$\Phi_{ST} - 2$ Bytes		

Table 3: RF-packet format for fragmented data of the high throughput mode

has been introduced in high throughput mode. Here up to 4 packets can be sent per connection interval. The sequence number and fragment ID are used to fragment and defragment the payload packet of Φ_{HTM} bytes into 4 packets, each of ($\Phi_{ST} - 2$) bytes size.

- Sequence number is a random number, that has to be the same for all fragments of a fragmented packet, but should differ for each packet.
- Fragment ID is of the structure **0xAB** and will define the order of the fragments to be defragmented/combined again
 - A the first 4 bits define the current fragment number (starting with 1)
 - **B** the last 4 bits define the overall number of fragments



2.2.1 Example: Transmitting fragmented data

Let us assume that we have a fragment payload size of 5 Bytes, the random number has been chosen as 0x00 and we suppose to send data consisting of 12 Bytes 0xE1 - 0xEC. Then 3 fragments of the following structure have to be transmitted:

Header	Sequence number	Fragment ID	Payload
0x04	0x00	0x13	0xE1 0xE2 0xE3 0xE4 0xE5

Table 4: Fragment 1

Header	Sequence number	Fragment ID	Payload
0x04	0x00	0x23	0xE6 0xE7 0xE8 0xE9 0xEA

Table 5: Fragment 2

Header	Sequence number	Fragment ID	Payload
0x04	0x00	0x33	0xEB 0xEC

Table 6: Fragment 3

When receiving fragmented data packets with header **0x04**, the fragments are combined and output by a CMD_DATA_IND message on the UART only if:

- all fragments have been received
- all fragments have the same overall number of fragments number (**B**, i.e. the last 4 bits of the **Fragment ID**)
- all fragments contain the same sequence number

In a case where at least one of this conditions is not satisfied the data will be discarded without further notice.



3 Throughput test

This chapter describes the throughput tests that have been performed. The following devices have been tested:

- Proteus-II in FW version 1.1.0
- Proteus-III in FW version 1.1.0
- Proteus-III SPI in FW version 1.2.0

3.1 Test conditions

To get the best throughput performance we choose the following settings of the Proteus module:

- The Proteus module operates in command mode.
- The UART/SPI must be set to maximum speed:
 - Proteus-II: The UART runs with baudrate 921600 Baud, 8n1, and uses the flow control pins *RTS* and *CTS*.
 - Proteus-III: The UART runs with baudrate 1000000 Baud, 8n1, and uses the flow control pins *RTS* and *CTS*.
 - Proteus-III SPI: The SPI runs with a datarate of 8 Mbit.
- The connection interval has been set to a fast value depending on the devices used (see chapter 3.3).
- Set the module to high throughput mode by setting the corresponding bit in the CFG_Flags.
- The 2 Mbit mode PHY is used for fastest radio data transmission.



If data is transmitted from one Proteus module to another, both modules must be configured in the same manner.

3.2 Test procedure

The test procedure is as follows:

- 1. Setup a Bluetooth connection between the two Bluetooth[®] LE enabled devices. We call them here device A to device B.
- 2. Check if large data packets are supported, by reading the maximum transmission unit (MTU) from the CMD_CHANNELOPEN_RSP message during connection setup. The maximum supported data packets Φ_{ST} are:
 - a) Proteus to Proteus: Φ_{ST} = 243 (0xF3) Bytes

- b) Proteus to Android device: Φ_{ST} = 243 (0xF3) Bytes
- c) Proteus to iOS device: Φ_{ST} = 181 (0xB5) Bytes
- 3. Switch the PHY to 2 Mbit using the CMD_PHYUPDATE_REQ command.
- 4. Iterate over:
 - a) Transmit a data packet of maximum size Φ_{HTM} Bytes using a CMD_DATA_REQ command. Φ_{HTM} calculates as:
 - i. Proteus to Proteus: Φ_{HTM} = (243 3 + 1) × 4 = 964 Bytes
 - ii. Proteus to Android device: $\Phi_{HTM} = (243 3 + 1) \times 4 = 964$ Bytes
 - iii. Proteus to iOS device: $\Phi_{HTM} = (181 3 + 1) \times 4 = 716$ Bytes
 - b) Wait for the transmission success message (CMD_TXCOMPLETE_IND) that is returned on the UART as result of the previous transmission request.

3.3 Test results

The throughput tests have been performed in two different test setups.

3.3.1 Test setup 1: Via USB interface and PC

The Proteus modules are connected via FTDI-chip and USB cable to a PC. A PC tool triggers the repeated data transmission. In this case the USB latencies slow down the data transmission.

Device A	Device B	Connection interval [ms]	Throughput [kBytes/s]
Proteus-II	Proteus-II	7.5 - 7.5	24.7
Proteus-II	Proteus-II	7.5 - 30	16
Proteus-II	Proteus-II	20 - 75	6.3
Samsung Galaxy S8 (SM-G950F, Android 8.0)	Proteus-II	7.5 - 7.5	18.1
Samsung Galaxy S8 (SM-G950F, Android 8.0)	Proteus-II	7.5 - 30	11.28
Samsung Galaxy S8 (SM-G950F, Android 8.0)	Proteus-II	20 - 75	9.7
iPhone 7 (MN922 ZD/A, iOS 11.4)	Proteus-II	7.5 - 30	8.125
iPhone 7 (MN922 ZD/A, iOS 11.4)	Proteus-II	20 - 75	8.125

Table 7: Test results Proteus-II via USB

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Device A	Device B	Connection interval [ms]	Throughput [kBytes/s]
Proteus-III	Proteus-III	7.5 - 7.5	21.3
Proteus-III	Proteus-III	7.5 - 30	15.9
Proteus-III	Proteus-III	20 - 75	6.3
Samsung Galaxy S8 (SM-G950F, Android 8.0)	Proteus-III	7.5 - 7.5	18.9
Samsung Galaxy S8 (SM-G950F, Android 8.0)	Proteus-III	7.5 - 30	8
Samsung Galaxy S8 (SM-G950F, Android 8.0)	Proteus-III	20 - 75	6.16
iPhone XS (iOS 12.2)	Proteus-III	7.5 - 30	8.7
iPhone XS (iOS 12.2)	Proteus-III	20 - 75	8.2

Table 8: Test results Proteus-III via USB

3.3.2 Test setup 2: Via micro controller

The Proteus modules' UARTs/SPIs are directly connected to a micro controller², that triggers the repeated data transmission.

Device A	Device B	Connection interval [ms]	Throughput [kBytes/s]
Proteus-II	Proteus-II	7.5 - 7.5	32.17
Proteus-II	Proteus-II	7.5 - 30	16.07
Proteus-II	Proteus-II	20 - 75	6.78
Samsung Galaxy S8 (Model SM-G950F, Android 8.0)	Proteus-II	7.5 - 7.5	28.60
Samsung Galaxy S8 (Model SM-G950F, Android 8.0)	Proteus-II	7.5 - 30	16.07
Samsung Galaxy S8 (Model SM-G950F, Android 8.0)	Proteus-II	20 - 75	9.93
iPhone 7 (MN922 ZD/A, iOS 11.4)	Proteus-II	7.5 - 30	12.13
iPhone 7 (MN922 ZD/A, iOS 11.4)	Proteus-II	20 - 75	11.21

Table 9: Test results Proteus-II via micro controller

²In this test a STM32 on a NUCLEOL476RG has been used.

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Device A	Device B	Connection interval [ms]	Throughput [kBytes/s]
Proteus-III	Proteus-III	7.5 - 7.5	42.9
Proteus-III	Proteus-III	7.5 - 30	16.43
Proteus-III	Proteus-III	20 - 75	6.75
Samsung Galaxy S8 (Model SM-G950F, Android 8.0)	Proteus-III	7.5 - 7.5	28.69
Samsung Galaxy S8 (Model SM-G950F, Android 8.0)	Proteus-III	7.5 - 30	16.07
Samsung Galaxy S8 (Model SM-G950F, Android 8.0)	Proteus-III	20 - 75	6.30
iPhone XS (iOS 12.2)	Proteus-III	8 - 30	11.95
iPhone XS (iOS 12.2)	Proteus-III	20 - 75	11.95

Table 10: Test results Proteus-III via micro controller

Device A	Device B	Connection interval [ms]	Throughput [kBytes/s]
Proteus-III-SPI	Proteus-III-SPI	7.5 - 7.5	64.3
Proteus-III-SPI	Proteus-III-SPI	7.5 - 30	16.07
Proteus-III-SPI	Proteus-III-SPI	20 - 75	12.85
Samsung Galaxy S8 (Model SM-G950F, Android 8.0)	Proteus-III-SPI	7.5 - 7.5	42.88
Samsung Galaxy S8 (Model SM-G950F, Android 8.0)	Proteus-III-SPI	7.5 - 30	16.07
Samsung Galaxy S8 (Model SM-G950F, Android 8.0)	Proteus-III-SPI	20 - 75	6.42

Table 11: Test results Proteus-III SPI via micro controller



4 Important notes

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